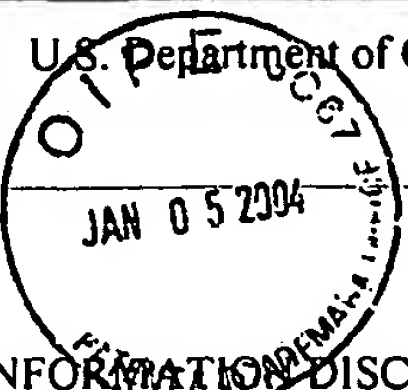


U.S. Department of Commerce, Patent and Trademark Office INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Application No.:	09/788,273
	Filing Date:	Feb. 16, 2001
	First Named Inventor:	Jiping Li
	Group Art Unit:	2823
	Examiner Name:	Michelle Estrada
	Confirmation No.:	6335
	Attorney Docket No.:	BOX009 US

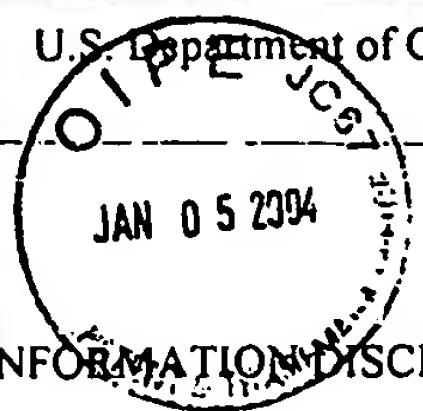
Foreign Patent Documents								
							Translation	
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Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)								
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*Examiner Initials		Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate
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<i>ME</i>	2.	6,154,280	11/2/00	Borden	356	376	
<i>ME</i>	3.	5,883,518	3/16/99	Borden	324	752	
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